TYN16B-600CT

SCR

Rev. 01 - 15 May 2017 Product data sheet

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a TO263 (D2PAK) plastic package intended for use in applications requiring high thermal cycling performance and high junction temperature capability ($T_{j(max)}$ = 150 °C).

2. Features and benefits

- High junction operating temperature capability
- High thermal cycling performance
- High voltage capability
- Planar passivated for voltage ruggedness and reliability
- High bidirectional blocking voltage capability
- Surface mountable package
- Very high current surge capability

3. Applications

- Ignition circuits
- Motor control
- Protection circuits e.g. SMPS inrush current
- Voltage regulation
- Crowbar protection

4. Quick reference data

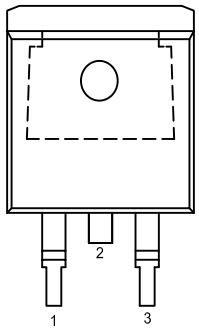
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage			-	-	600	V
V_{RRM}	repetitive peak reverse voltage			-	-	600	V
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig. 4; Fig. 5		-	-	180	A
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms		-	-	198	A
T_j	junction temperature			-	-	150	°C
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq$ 133 °C; Fig. 1		-	-	10.2	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq$ 133 °C; Fig. 2; Fig. 3		-	-	16	A

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 7		1.5	-	6	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit		300	-	-	V/µs

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 **D2PAK (TO263N)**	
2	A	anode		
3	G	gate		
mb	mb	mounting base; connected to anode		

6. Ordering information

Table 3. Ordering information

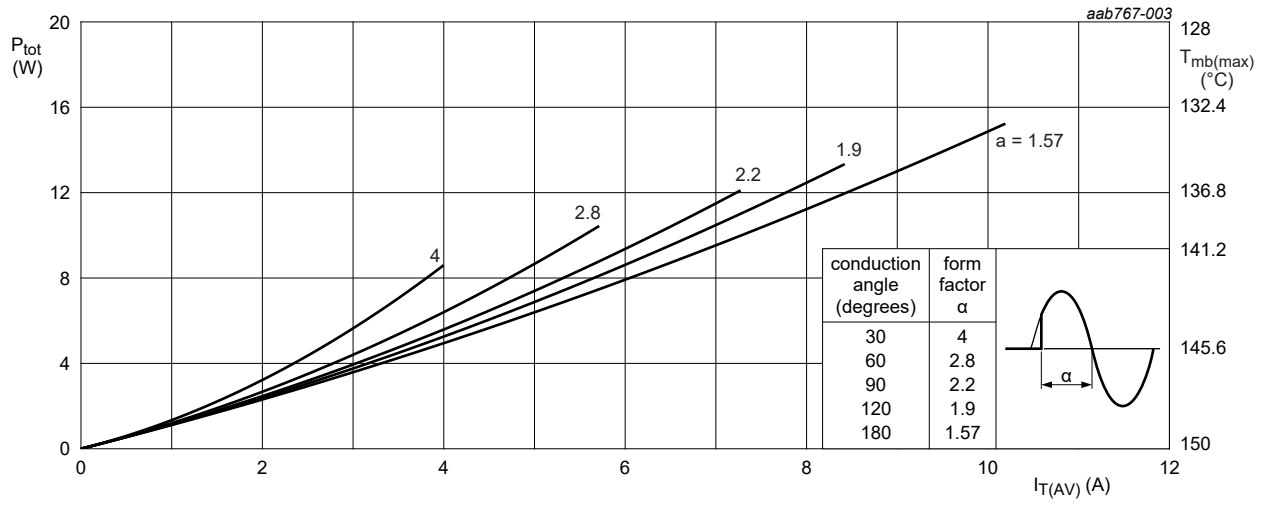
Type number	Package		
	Name	Description	Version
TYN16B-600CT	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	TO263N

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage			-	600	V
V_{RRM}	repetitive peak reverse voltage			-	600	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq$ 133 °C; Fig. 1		-	10.2	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq$ 133 °C; Fig. 2; Fig. 3		-	16	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig. 4; Fig. 5		-	180	A
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms		-	198	A
I^2t	I^2t for fusing	t_p = 10 ms; SIN		-	162	A^2s
dI_T/dt	rate of rise of on-state current	I_G = 30 mA		-	50	A/µs
I_{GM}	peak gate current			-	4	A
V_{RGM}	peak reverse gate voltage			-	5	V
P_{GM}	peak gate power			-	10	W
$P_{G(AV)}$	average gate power	over any 20 ms period		-	1	W
T_{stg}	storage temperature			-40	150	°C
T_j	junction temperature			-	150	°C



α = conduction angle

a = form factor = $I_{T(RMS)}$ / $I_{T(AV)}$

Fig. 1. Total power dissipation as a function of average on-state current; maximum values

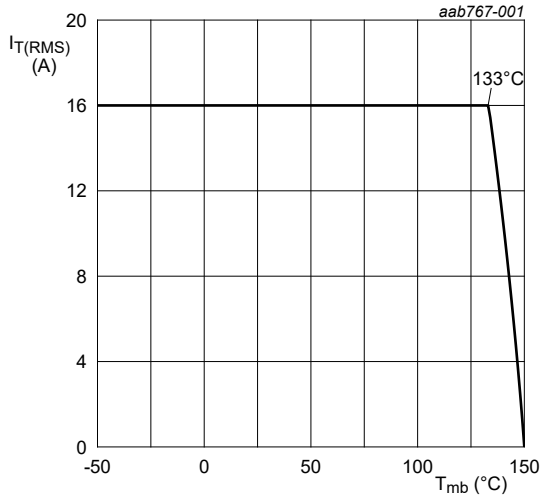
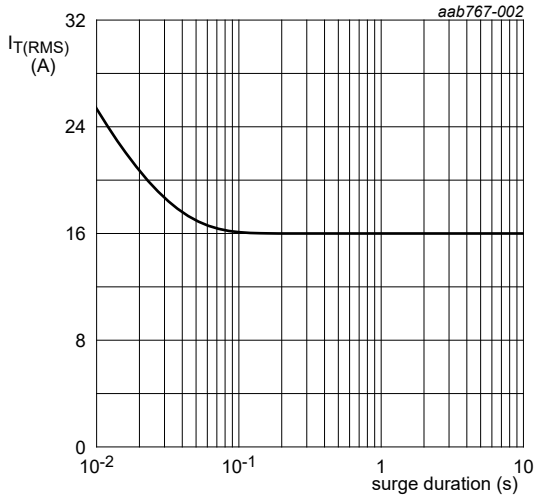
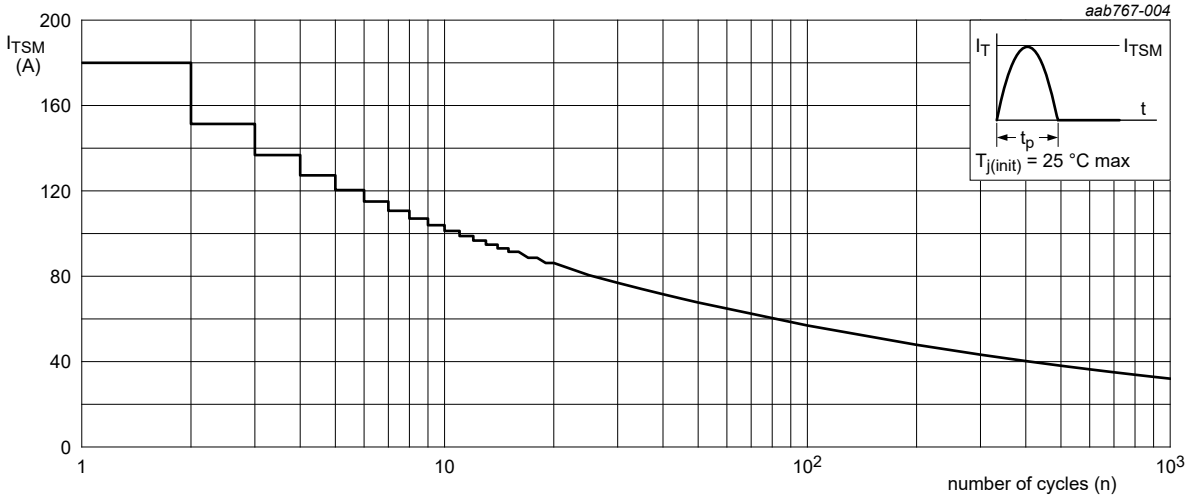


Fig. 2. RMS on-state current as a function of mounting base temperature; maximum values



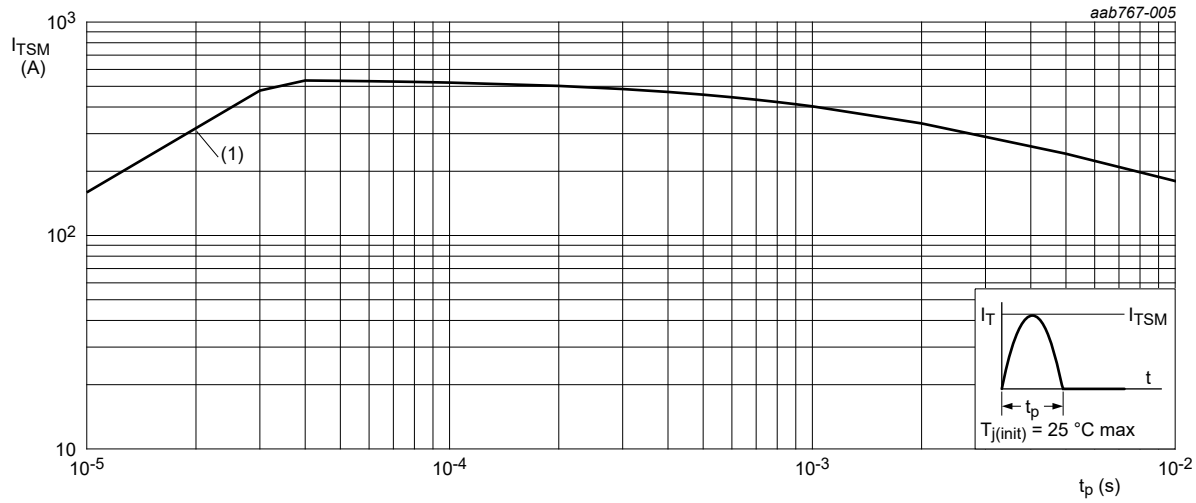
f = 50 Hz; T_{mb} = 133 °C

Fig. 3. RMS on-state current as a function of surge duration; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 10$ ms
(1) dI_T/dt limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6		-	-	1.1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	mounted on a minimum footprint FR4 board		-	55	-	K/W

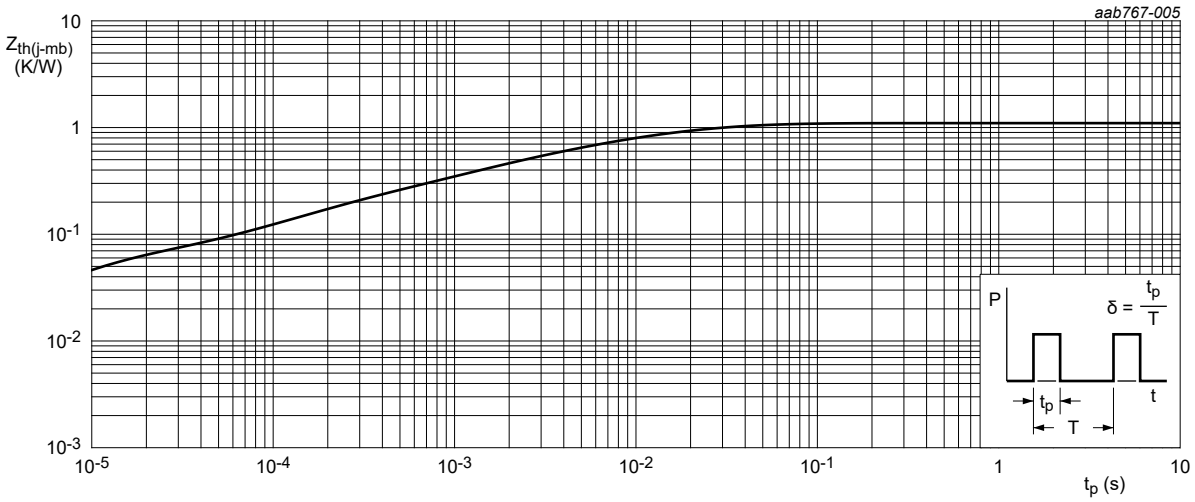


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 7		1.5	-	6	mA
I_L	latching current	V_D = 12 V; I_G = 0.1 A; T_j = 25 °C; Fig. 8		-	-	60	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C; Fig. 9		-	-	40	mA
V_T	on-state voltage	I_T = 32 A; T_j = 25 °C; Fig. 10		-	1.2	1.6	V
V_{GT}	gate trigger voltage	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 11		-	0.7	1.3	V
		V_D = 400 V; I_T = 0.1 A; T_j = 150 °C; Fig. 11		0.2	0.4	-	V
I_D	off-state current	V_D = 600 V; T_j = 150 °C		-	-	1	mA
I_R	reverse current	V_R = 600 V; T_j = 150 °C		-	-	1	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit		300	-	-	V/µs
		V_{DM} = 402 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit		100	-	-	V/µs

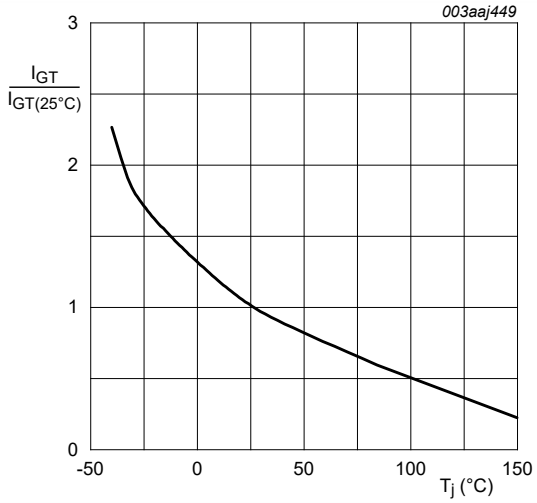


Fig. 7. Normalized gate trigger current as a function of junction temperature

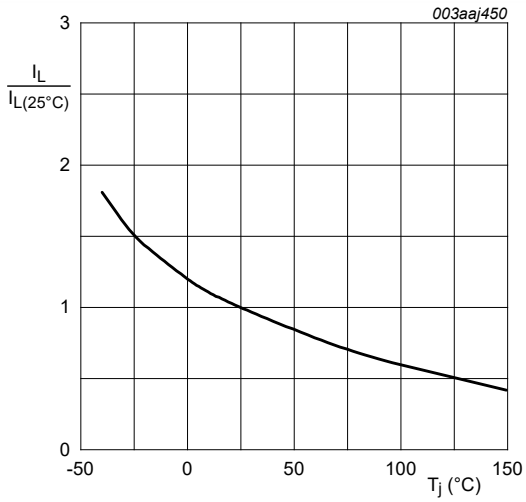


Fig. 8. Normalized latching current as a function of junction temperature

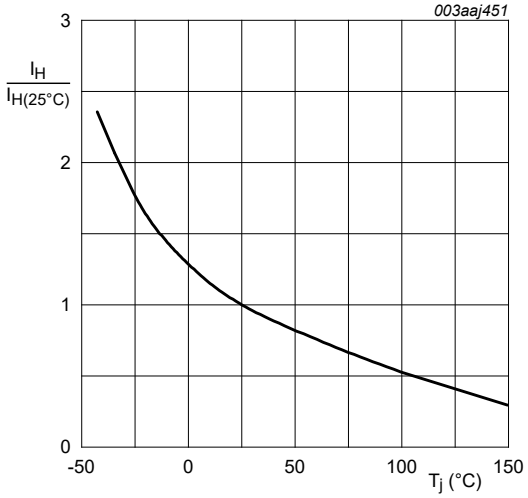
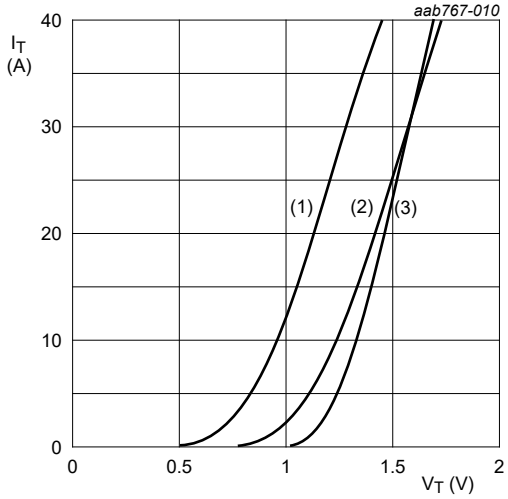


Fig. 9. Normalized holding current as a function of junction temperature



V_o = 1.071 V; R_s = 0.0169 Ω
(1) T_j = 150 °C; typical values
(2) T_j = 150 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

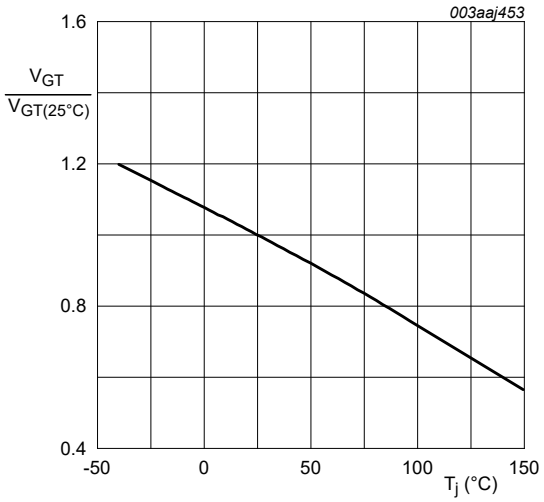
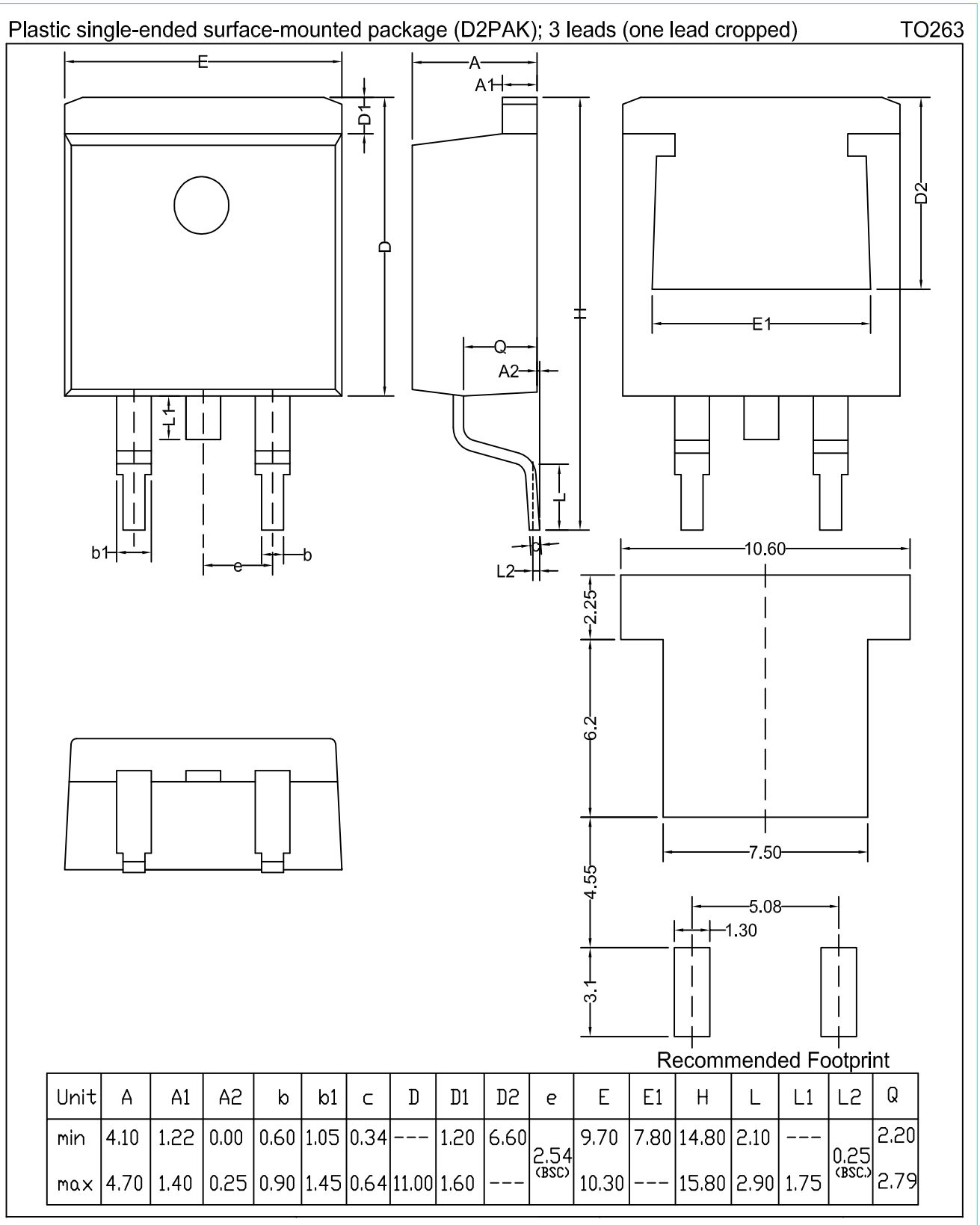


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

10. Package outline



Unit	A	A1	A2	b	b1	c	D	D1	D2	e	E	E1	H	L	L1	L2	Q
min	4.10	1.22	0.00	0.60	1.05	0.34	---	1.20	6.60	2.54 (BSC)	9.70	7.80	14.80	2.10	---	0.25 (BSC)	2.20
max	4.70	1.40	0.25	0.90	1.45	0.64	11.00	1.60	---		10.30	---	15.80	2.90	1.75		2.79

Fig. 12. Package outline D2PAK (TO263N)

11. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".
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12. Contents

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